IPC ASSOCIATION CONNECTINE ELECTRONICS INDUSTRIE	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowel parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.												
752-21.1		IPC Web Site for Information on IPC-1752 Standard  Form Typ  http://www.ipc.org/IPC-175x  Form Typ  Distribute				pe * e	e * Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater						ials and Mfg Information				
Supplier Inforn	nation																
Company name*				Company unique ID			Unique ID Authority					Response Date*					
nsemi												2024-05-02					
Contact Name		Title - Contact			]	Phone - Contact*					Email - Contact*						
Product-Env-Stewa	ards	Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com						
uthorized Represe	entative*	Title - Representative			]	Phone - Representative*				Email - Representative*							
Product-Env-Stewards			Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com					
Requesto	er Item Number	Mfr Item	tem Number Mfr Item Name				Effective Da	ate V	ersion	Manufacturing Site		7	Weight*		UOM	Unit Type	
				3.3 V Automotive Receiver	3 V Automotive Grade LVDS Line sceiver		2024-05-02			THE	ТНВ		5.516		mg	Each	
<b>Ianufacturing</b>	Proccess Information	n															
Terminal	Plating / Grid Array Material		Ferminal Base Alloy J		J-STD-020 M	ISL Rating	Peak Pr	Peak Process Body Temperature		ature 1	Max Time at Peak	Temperat	ıre N	Number (	of Reflow Cyc	les	
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)		Au) (no	CU Alloy 1		1		260		С		30 seco		ds 3	3			
Comments																	
vel 1 - maximum t	ime at peak temperature	during sol	ldering is 10-3	0 seconds													
or more informati	on regarding material co	mposition	please refer to	page 3													

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.373	mg	Supplier	Silicon (Si)	7440-21-3		0.373	mg
Die Attach Epoxy	0.001	mg	Supplier	Poly(oxypropylene)diamine	9046-10-0		0	mg
			Supplier	Silver (Ag)	7440-22-4		0.0009	mg
			Supplier	Proprietary	Proprietary Data		0.0001	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.0001	mg
Lead Frame	1.117	mg	Supplier	Zinc (Zn)	7440-66-6		0.0013	mg
			Supplier	Iron (Fe)	7439-89-6		0.0262	mg
			Supplier	Copper (Cu)	7440-50-8		1.0891	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0003	mg
Mold Compound-Black	13.04	mg		Epoxy resin	proprietary data		0.652	mg
			Supplier	Phenolic Resin	Proprietary Data		0.2608	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.326	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0652	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		11.736	mg
Plating	0.923	mg	Supplier	Palladium (Pd)	7440-05-3		0.0701	mg
			В	Nickel (Ni)	7440-02-0		0.8399	mg
			Supplier	Gold (Au)	7440-57-5		0.0129	mg
Wire Bond - Au	0.062	mg	Supplier	Gold (Au)	7440-57-5		0.062	mg